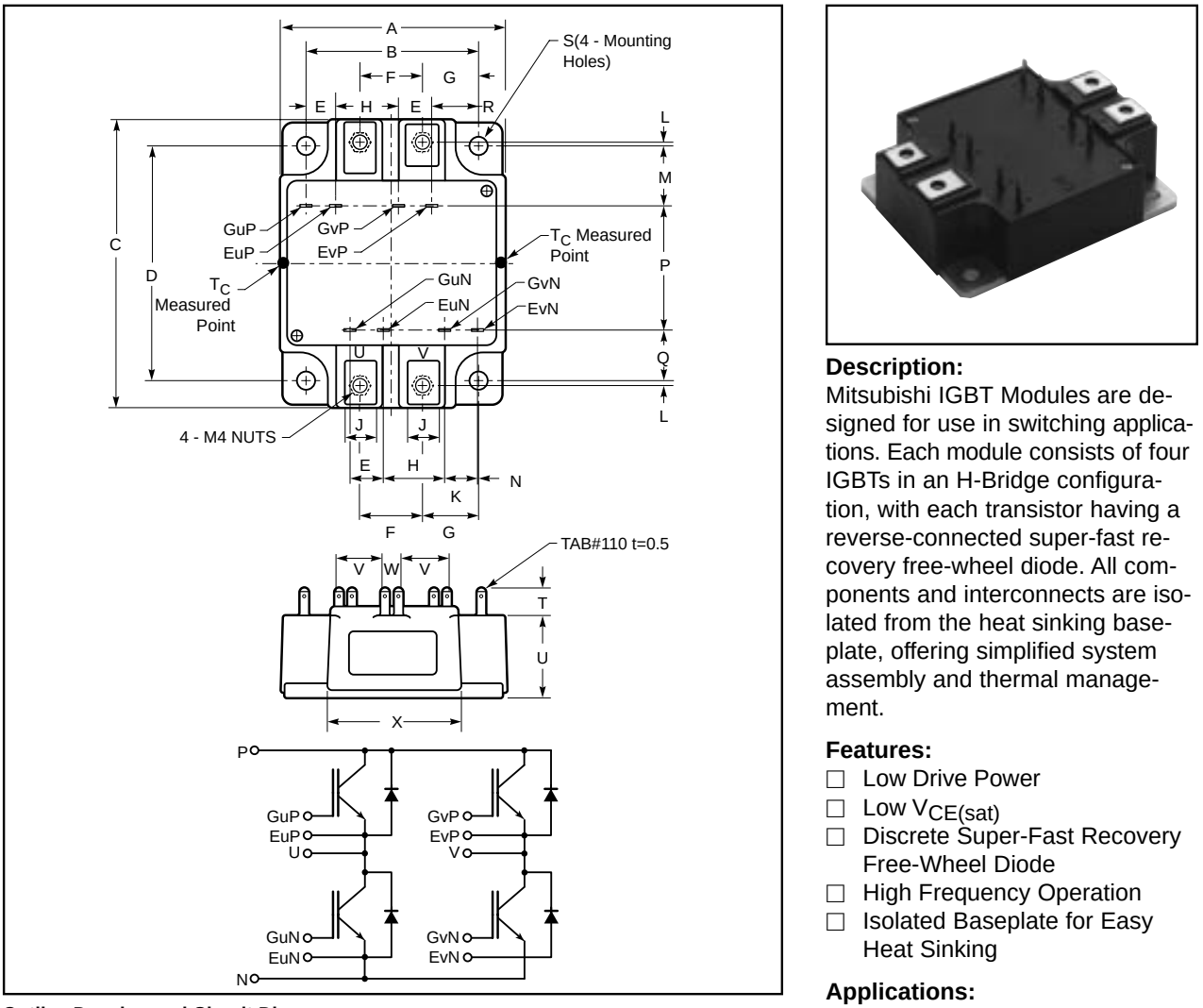
MITSUBISHI IGBT MODULES

CM75BU-12H

HIGH POWER SWITCHING USE INSULATED TYPE



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	2.83	72.0
B	2.17±0.01	55±0.25
C	3.58	91.0
D	2.91±0.01	74.0±0.25
E	0.43	11.0
F	0.79	20.0
G	0.69	17.5
H	0.75	19.1
J	0.39	10.0
K	0.41	10.5
L	0.05	1.25

Dimensions	Inches	Millimeters
M	0.74	18.7
N	0.02	0.5
P	1.55	39.3
Q	0.63	16.0
R	0.57	14.4
S	0.22 Dia.	5.5 Dia.
T	0.32	8.1
U	1.02	26.0
V	0.59	15.0
W	0.20	5.0
X	1.61	41.0

Description:
Mitsubishi IGBT Modules are designed for use in switching applications. Each module consists of four IGBTs in an H-Bridge configuration, with each transistor having a reverse-connected super-fast recovery free-wheel diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

Features:
- ☐ Low Drive Power
- ☐ Low $V_{CE(sat)}$
- ☐ Discrete Super-Fast Recovery Free-Wheel Diode
- ☐ High Frequency Operation
- ☐ Isolated Baseplate for Easy Heat Sinking

Applications:
- ☐ AC Motor Control
- ☐ Motion/Servo Control
- ☐ UPS
- ☐ Welding Power Supplies

Ordering Information:
Example: Select the complete module number you desire from the table - i.e. CM75BU-12H is a 600V (V_{CES}), 75 Ampere Four-IGBT Module.

Type	Current Rating Amperes	V_{CES} Volts (x 50)
CM	75	12

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Absolute Maximum Ratings, T_j = 25 °C unless otherwise specified

Ratings	Symbol	CM75BU-12H	Units
Junction Temperature	T_j	-40 to 150	°C
Storage Temperature	T_{stg}	-40 to 125	°C
Collector-Emitter Voltage (G-E SHORT)	V_{CES}	600	Volts
Gate-Emitter Voltage (C-E SHORT)	V_{GES}	±20	Volts
Collector Current (T_c = 25°C)	I_C	75	Amperes
Peak Collector Current ($T_j \leq$ 150°C)	I_{CM}	150*	Amperes
Emitter Current** (T_c = 25°C)	I_E	75	Amperes
Peak Emitter Current**	I_{EM}	150*	Amperes
Maximum Collector Dissipation (T_c = 25°C)	P_c	310	Watts
Mounting Torque, M4 Main Terminal	–	1.3 ~ 1.7	N · m
Mounting Torque, M5 Mounting	–	2.5 ~ 3.5	N · m
Weight	–	390	Grams
Isolation Voltage (Main Terminal to Baseplate, AC 1 min.)	V_{iso}	2500	Vrms

* Pulse width and repetition rate should be such that the device junction temperature (T_j) does not exceed $T_{j(max)}$ rating.
**Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDi).

Static Electrical Characteristics, T_j = 25 °C unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector-Cutoff Current	I_{CES}	$V_{CE} = V_{CES}$, V_{GE} = 0V	–	–	1	mA
Gate Leakage Voltage	I_{GES}	$V_{GE} = V_{GES}$, V_{CE} = 0V	–	–	0.5	µA
Gate-Emitter Threshold Voltage	$V_{GE(th)}$	I_C = 7.5mA, V_{CE} = 10V	4.5	6	7.5	Volts
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	I_C = 75A, V_{GE} = 15V, T_j = 25°C	–	2.4	3.0	Volts
		I_C = 75A, V_{GE} = 15V, T_j = 125°C	–	2.6	–	Volts
Total Gate Charge	Q_G	V_{CC} = 300V, I_C = 75A, V_{GE} = 15V	–	150	–	nC
Emitter-Collector Voltage*	V_{EC}	I_E = 75A, V_{GE} = 0V	–	–	2.6	Volts

* Pulse width and repetition rate should be such that the device junction temperature (T_j) does not exceed $T_{j(max)}$ rating.

Dynamic Electrical Characteristics, T_j = 25 °C unless otherwise specified

Characteristics		Symbol	Test Conditions	Min.	Typ.	Max.	Units
Input Capacitance		C_{ies}	V_{CE} = 10V, V_{GE} = 0V	–	–	6.6	nF
Output Capacitance		C_{oes}		–	–	3.6	nF
Reverse Transfer Capacitance		C_{res}		–	–	1.0	nF
Resistive	Turn-on Delay Time	$t_{d(on)}$	V_{CC} = 300V, I_C = 75A,	–	–	100	ns
Load	Rise Time	t_r	$V_{GE1} = V_{GE2}$ = 15V,	–	–	250	ns
Switch	Turn-off Delay Time	$t_{d(off)}$	R_G = 8.3Ω, Resistive	–	–	200	ns
Times	Fall Time	t_f	Load Switching Operation	–	–	300	ns
Diode Reverse Recovery Time		t_{rr}	I_E = 75A, di_E/dt = -150A/µs	–	–	160	ns
Diode Reverse Recovery Charge		Q_{rr}	I_E = 75A, di_E/dt = -150A/µs	–	0.18	–	µC

Thermal and Mechanical Characteristics, T_j = 25 °C unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case	$R_{th(j-c)}Q$	Per IGBT 1/4 Module	–	–	0.4	°C/W
Thermal Resistance, Junction to Case	$R_{th(j-c)}D$	Per FWDi 1/4 Module	–	–	0.9	°C/W
Contact Thermal Resistance	$R_{th(c-f)}$	Per Module, Thermal Grease Applied	–	0.025	–	°C/W

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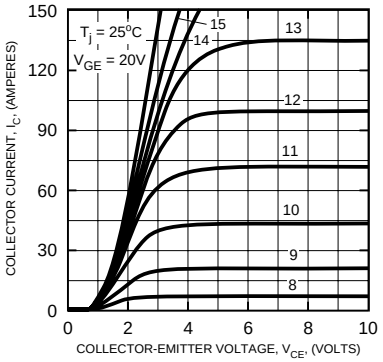
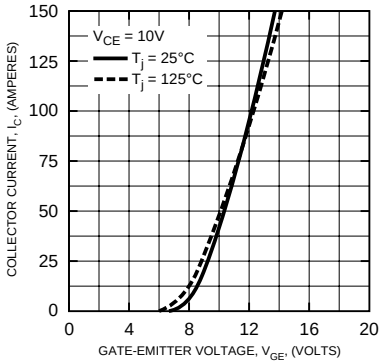
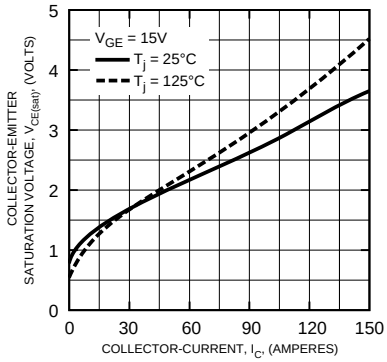
OUTPUT CHARACTERISTICS (TYPICAL)



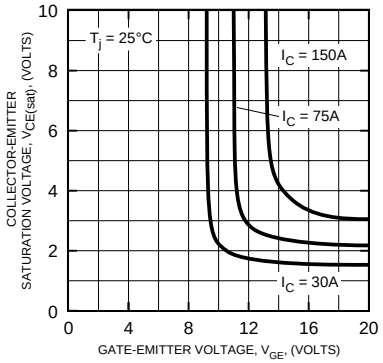
TRANSFER CHARACTERISTICS (TYPICAL)



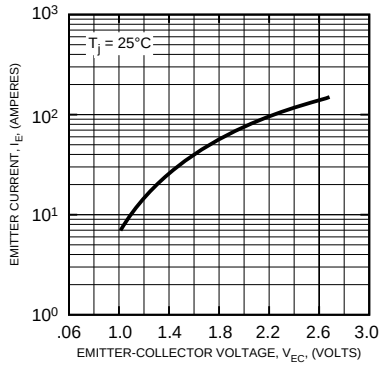
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



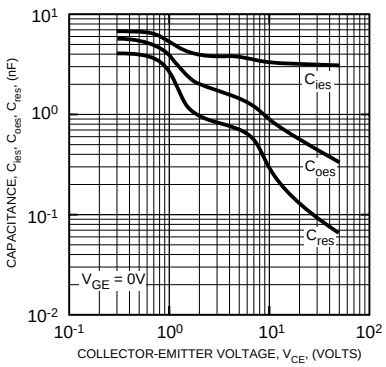
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



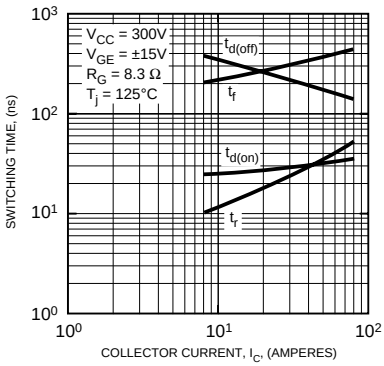
FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)



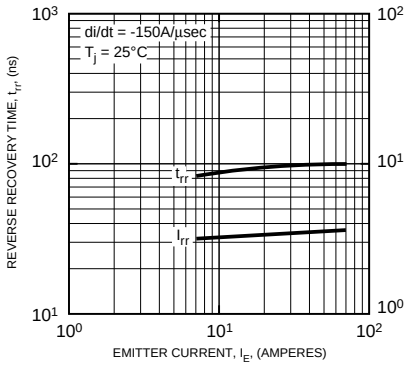
CAPACITANCE VS. V_{CE} (TYPICAL)



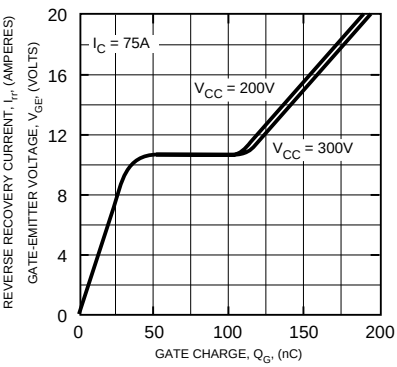
HALF-BRIDGE SWITCHING CHARACTERISTICS (TYPICAL)



REVERSE RECOVERY CHARACTERISTICS (TYPICAL)



GATE CHARGE, V_{GE}



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